

Features

- Medium current Triac
- Low thermal resistance with clip bonding
- Low thermal resistance insulation ceramic for insulated BTA
- High commutation (4Q) or very high commutation (3Q) capability
- BTA series UL1557 certified (File ref: 81734)
- RoHS (2002/95/EC) compliant
- Insulated tab (BTA series, rated at 2500 V_{RMS})

**TO-220AB
insulated
BTA16**



**TO-220AB
BTB16**



Applications

- Snubberless versions (BTA/BTB...W and T1635) especially recommended for use on inductive loads, because of their high commutation performances
- On/off or phase angle function in applications such as static relays, light dimmers and appliance motor speed controllers

**D²PAK
T1610G**



Description

Available either in through-hole or surface-mount packages, the BTA16, BTB16, T1610 and T1635 Triacs series are suitable for general purpose mains power AC switching.

Table 1. Device summary

| Symbol | Parameter | BTA16 ⁽¹⁾ | BTB16 | T1610 | T1635 |
|----------------------------------|-----------------------------------|----------------------|---------|---------|---------|
| I _{T(RMS)} | On-state rms current | 16 | 16 | 16 | 16 |
| V _{DRM/V_{RRM}} | Repetitive peak off-state voltage | 600/800 | 600/800 | 600/800 | 600/800 |
| I _{GT} (Snubberless) | Triggering gate current | 35/50 | 35/50 | - | 35 |
| I _{GT} (logic level) | Triggering gate current | 10 | 10 | 10 | - |
| I _{GT} (standard) | Triggering gate current | 25/50 | 25/50 | - | - |

1. Insulated

TM: Snubberless is a trademark of STMicroelectronics

Table 2. Absolute maximum ratings

| Symbol | Parameter | | | Value | Unit | | |
|-------------------|--|--|----------------------------------|----------------|----------------------------|--|--|
| $I_{T(RMS)}$ | On-state rms current (full sine wave) | | D ² PAK / TO-220AB | 16 | A | | |
| | | | TO-220AB insulated | | | | |
| I_{TSM} | Non repetitive surge peak on-state current (full cycle, T_j initial = 25 °C) | | F = 50 Hz | t = 20 ms | 160 | | |
| | | | F = 60 Hz | t = 16.7 ms | 168 | | |
| I^2t | I^2t value for fusing | | $t_p = 10$ ms | | 144 | | |
| dI/dt | Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \leq 100$ ns | | F = 120 Hz | $T_j = 125$ °C | 50 | | |
| V_{DSM}/V_{RSM} | Non repetitive surge peak off-state voltage | | $t_p = 10$ ms | $T_j = 25$ °C | V_{DRM}/V_{RRM} + 100 | | |
| I_{GM} | Peak gate current | | $t_p = 20$ µs | $T_j = 125$ °C | 4 | | |
| $P_{G(AV)}$ | Average gate power dissipation | | $T_j = 125$ °C | | 1 | | |
| T_{stg} | Storage temperature range | | | | -40 to + 150 | | |
| T_j | Maximum operating junction temperature | | | | -40 to + 125 | | |

**Table 3. Electrical characteristics ($T_j = 25$ °C, unless otherwise specified)
Snubberless and logic level (3 quadrants)**

| Symbol | Test conditions | Quadrant | | T1610 | T1635 | BTA16 / BTB16 | | | Unit |
|---------------------------|---|----------------|------|-------|-------|---------------|-----|------|------|
| | | | | | | SW | CW | BW | |
| I_{GT} ⁽¹⁾ | $V_D = 12$ V | I - II - III | Max. | 10 | 35 | 10 | 35 | 50 | mA |
| V_{GT} | $R_L = 33$ Ω | I - II - III | Max. | | | 1.3 | | | V |
| V_{GD} | $V_D = V_{DRM}$ $R_L = 3.3$ kΩ $T_j = 125$ °C | I - II - III | Min. | | | 0.2 | | | V |
| I_H ⁽²⁾ | $I_T = 500$ mA | | Max. | 15 | 35 | 15 | 35 | 50 | mA |
| I_L | $I_G = 1.2 I_{GT}$ | I - III | Max. | 25 | 50 | 25 | 50 | 70 | mA |
| | | II | | 30 | 60 | 30 | 60 | 80 | |
| dV/dt ⁽²⁾ | $V_D = 67\%V_{DRM}$ gate open | $T_j = 125$ °C | Min. | 40 | 500 | 40 | 500 | 1000 | V/µs |
| $(dI/dt)c$ ⁽²⁾ | $(dV/dt)c = 0.1$ V/µs | $T_j = 125$ °C | Min. | 8.5 | - | 8.5 | - | - | A/ms |
| | $(dV/dt)c = 10$ V/µs | $T_j = 125$ °C | | 3.0 | - | 3.0 | - | - | |
| | Without snubber | $T_j = 125$ °C | | - | 8.5 | - | 8.5 | 14 | |

1. Minimum IGT is guaranteed at 5% of I_{GT} max

2. For both polarities of A2 referenced to A1

Table 4. Electrical characteristics ($T_j = 25^\circ\text{C}$, unless otherwise specified) standard (4 quadrants)

| Symbol | Test conditions | Quadrant | BTA16 / BTB16 | | Unit |
|------------------|---|---------------------------|---------------|------------|------------|
| | | | C | B | |
| $I_{GT}^{(1)}$ | $V_D = 12 \text{ V}$ $R_L = 33 \Omega$ | I - II - III IV | Max. | 25 50 | mA |
| V_{GT} | | ALL | Max. | 1.3 | V |
| V_{GD} | $V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$ $T_j = 125^\circ\text{C}$ | ALL | Min. | 0.2 | V |
| $I_H^{(2)}$ | $I_T = 500 \text{ mA}$ | | Max. | 25 50 | mA |
| I_L | $I_G = 1.2 I_{GT}$ | I - III - IV II | Max. | 40 80 | mA |
| $dV/dt^{(2)}$ | | $T_j = 125^\circ\text{C}$ | | 200 400 | |
| $(dV/dt)c^{(2)}$ | $(dI/dt)c = 7 \text{ A/ms}$ | $T_j = 125^\circ\text{C}$ | Min. | 5 10 | V/ μ s |

1. Minimum I_{GT} is guaranteed at 5% of I_{GT} max

2. For both polarities of A2 referenced to A1

Table 5. Static characteristics

| Symbol | Test conditions | | | Value | Unit |
|----------------|---------------------------|-------------------------|---------------------------|-------|------------------|
| $V_T^{(2)}$ | $I_{TM} = 22.5 \text{ A}$ | $t_p = 380 \mu\text{s}$ | $T_j = 25^\circ\text{C}$ | Max. | V |
| $V_{to}^{(2)}$ | Threshold voltage | | $T_j = 125^\circ\text{C}$ | Max. | V |
| $R_d^{(2)}$ | Dynamic resistance | | $T_j = 125^\circ\text{C}$ | Max. | $\text{m}\Omega$ |
| I_{DRM} | $V_{DRM} = V_{RRM}$ | | $T_j = 25^\circ\text{C}$ | Max. | μA |
| I_{RRM} | | | $T_j = 125^\circ\text{C}$ | | mA |

Table 6. Thermal resistance

| Symbol | Parameter | | | Value | Unit |
|---------------|-----------------------|--|-------------------------------|-------|--------------------|
| $R_{th(j-c)}$ | Junction to case (AC) | $D^2\text{PAK} / \text{TO}-220\text{AB}$ | | 1.2 | $^\circ\text{C/W}$ |
| | | TO-220AB insulated | | 2.1 | |
| $R_{th(j-a)}$ | Junction to ambient | $S^{(1)} = 1 \text{ cm}^2$ | $D^2\text{PAK}$ | 45 | $^\circ\text{C/W}$ |
| | | | TO-220AB / TO-220AB insulated | 60 | |

1. S = Copper surface under tab

Figure 1. Maximum power dissipation versus on-state rms current (full cycle)

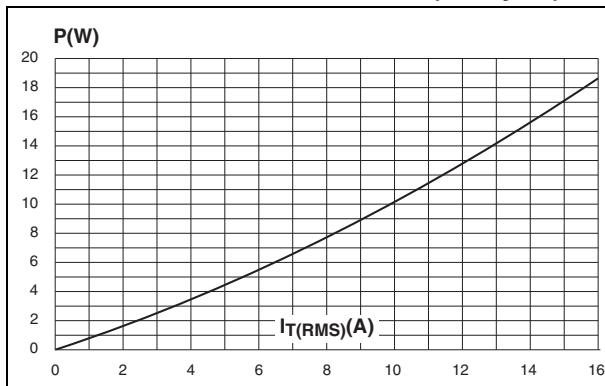


Figure 2. On-state rms current versus case temperature (full cycle)

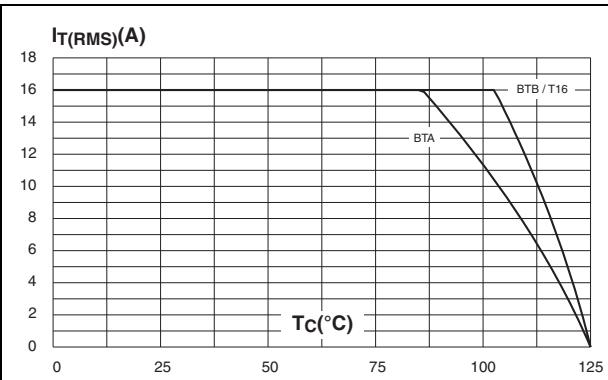


Figure 3. On-state rms current versus ambient temperature (full cycle)

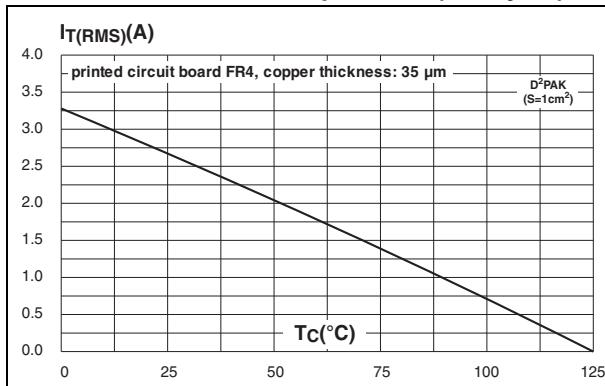


Figure 4. Relative variation of thermal impedance versus pulse duration

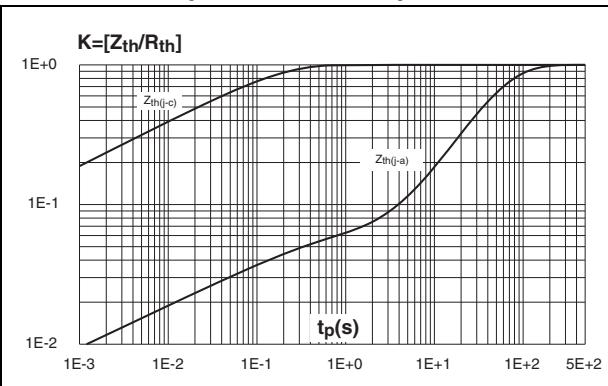


Figure 5. On-state characteristics (maximum values)

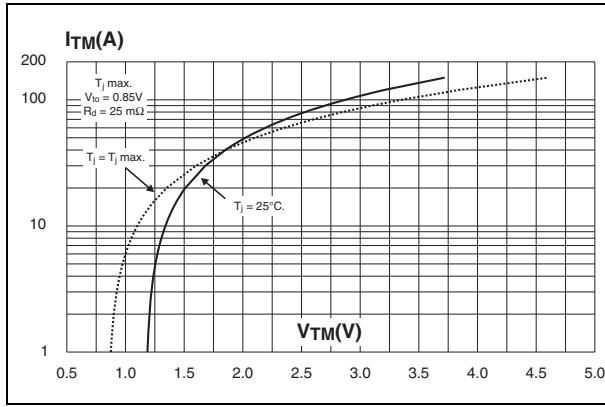


Figure 6. Surge peak on-state current versus number of cycles

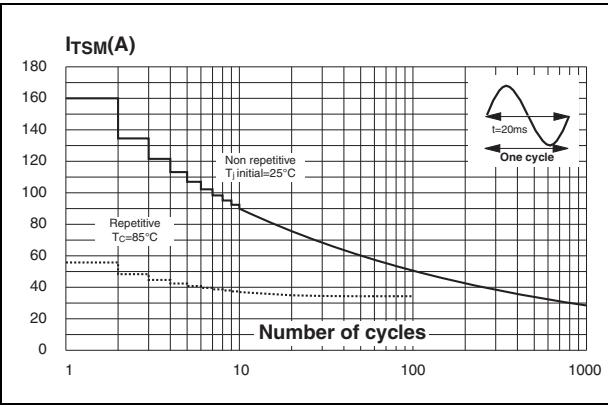


Figure 7. Non-repetitive surge peak on-state current for a sinusoidal

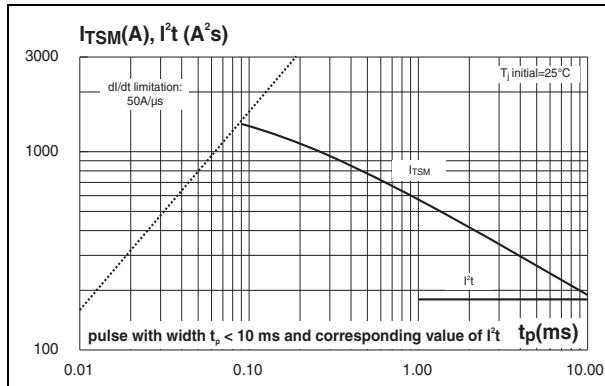


Figure 9. Relative variation of critical rate of decrease of main current versus $(dV/dt)c$ (typical values)

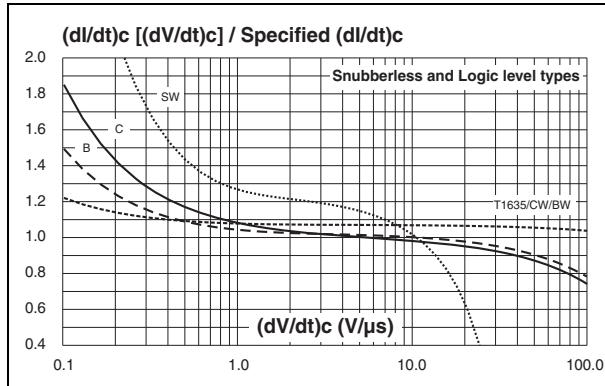


Figure 11. D²PAK thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: 35 μ m)

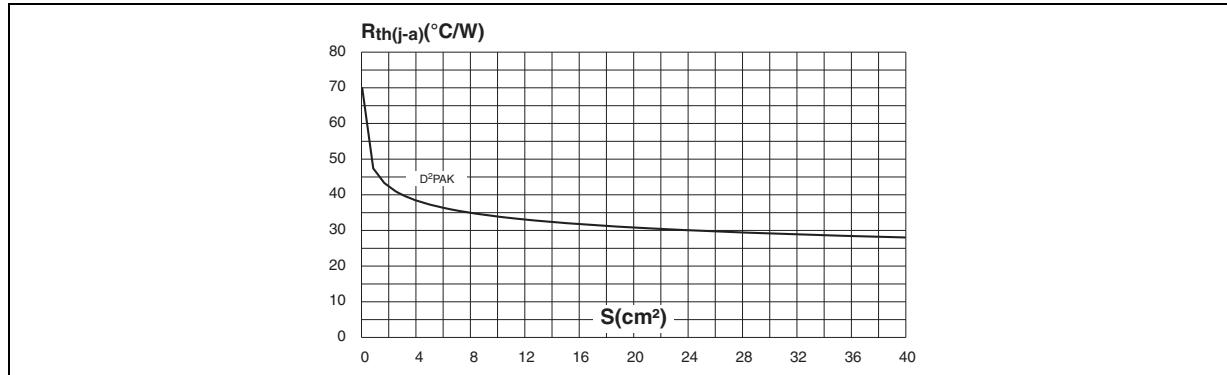
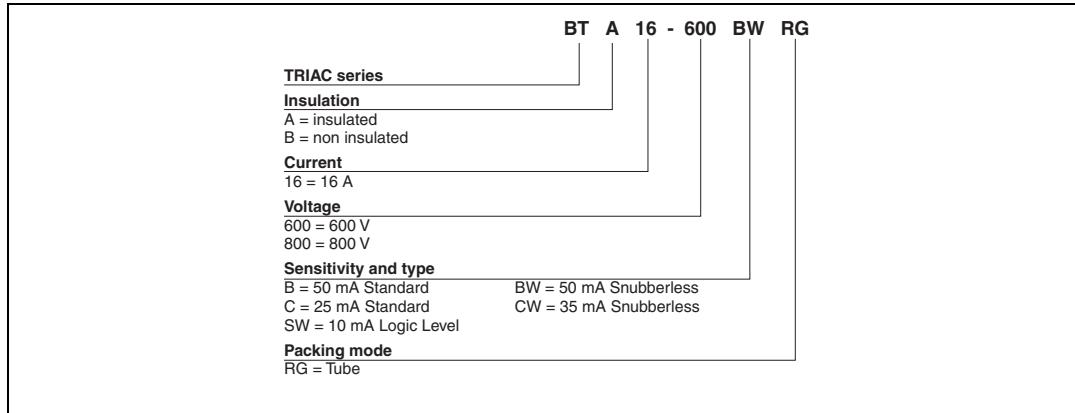
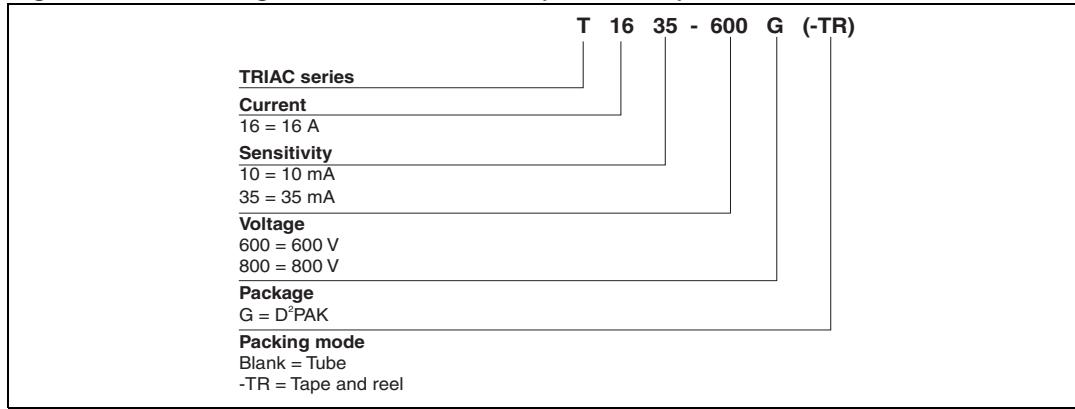


Figure 12. Ordering information scheme (BTA16 and BTB16 series)

Figure 13. Ordering information scheme (T16 series)

Table 7. Product selector

| Device ⁽¹⁾ | Voltage (xxx) | | Sensitivity | Type | Package |
|-----------------------|---------------|-------|-------------|-------------|--------------------|
| | 600 V | 800 V | | | |
| BTA/BTB16-xxxB | X | X | 50 mA | Standard | TO-220AB |
| BTA/BTB16-xxxBW | X | X | 50 mA | Snubberless | TO-220AB |
| BTA/BTB16-xxxC | X | | 25 mA | Standard | TO-220AB |
| BTA/BTB16-xxxCW | X | X | 35 mA | Snubberless | TO-220AB |
| BTA/BTB16-xxcSW | X | X | 10 mA | Logic level | TO-220AB |
| T1610-xxG | X | X | 10 mA | Logic level | D ² PAK |
| T1635-xxG | X | X | 35 mA | Snubberless | D ² PAK |

1. **BTB:** non insulated TO-220AB package